CLAIMS:

Please amend the claims as follows.

1. (Currently Amended) A method for manufacturing a flexible printed circuit bonded to a heat sink using a process that includes two bonding steps, the method comprising:

in a first bonding step, adhering a conductive layer to a first surface of a bond film using a first adhesive layer to produce a circuit substrate, wherein the adhering does not cause full curing of a second adhesive layer on a second surface of the bond film such that the second adhesive layer is B-staged; ~~is achieved by partially activating the first adhesive layer such that the conductive layer is tack-bonded to the bond film;~~

after the first bonding step, processing the circuit substrate to produce the flexible printed circuit, wherein the second adhesive layer remains B-staged during the processing; and

after the circuit substrate is processed, laminating the heat sink to the [[a]] second surface of the bond film of the flexible printed circuit, in a second bonding step, using [[a]] the second adhesive layer.

2. (Original) The method of claim 1, wherein the adhering of the conductive layer to the first surface of the bond film is performed in a temperature range of from about 100 to about 180 degrees Celsius and a pressure range of from about 50 to about 1000 pounds per square inch.

3. (Original) The method of claim 1, wherein the laminating of the heat sink to the second surface of the bond film is performed in a temperature range of from about 220 to about 300 degrees Celsius and a pressure range of from about 50 to about 1000 pounds per square inch.

4. (Original) The method of claim 1, wherein a composition of the first adhesive layer is different from a composition of the second adhesive layer.

5. (Original) The method of claim 4, wherein the compositions are selected to have different bonding temperatures.

6. (Original) The method of claim 1, wherein the processing comprises

imaging the conductive layer with a circuit pattern;

etching the imaged conductive layer to form circuit areas and etched areas, the circuit areas having predefined exposed areas and unexposed areas;

coating the etched areas and the predefined unexposed circuit areas with a protective dielectric material; and

coating the predefined exposed circuit areas with an antioxidant layer to produce the flexible printed circuit.

7. (Original) The method of claim 6, wherein the antioxidant layer comprises one selected from a polymer coating and a metal plating.

8. (Original) The method of claim 1, wherein the conductive layer comprises a copper foil.

9. (Original) The method of claim 1, wherein the adhering is performed in a pressed sheet manner.

10. (Original) The method of claim 1, wherein the adhering is performed in a roll-lamination fashion.

11. (Original) The method of claim 1, wherein the first adhesive layer is coated on the first surface of the bond film prior to the adhering.

12. (Original) The method of claim 1, wherein the first adhesive layer is coated on the conductive layer prior to the adhering.

13. (Previously Presented) The method of claim 1, wherein the second adhesive layer is coated on the second surface of the bond film prior to the adhering of the conductive layer to the first surface of the bond film.

14. (Previously Presented) The method of claim 1, wherein the second adhesive layer is coated on the second surface of the bond film after the adhering of the conductive layer to the first surface of the bond film, and prior to the laminating the heat sink to the second surface of the bond film.

15. (Original) The method of claim 1, wherein the second adhesive layer is coated on the heat sink prior to the laminating the heat sink to the second surface of the bond film.

16. (New) The method of claim 1, wherein the second adhesive layer comprises thermoplastic polyimide.